



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

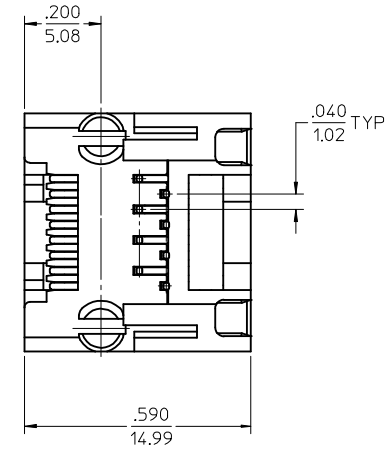
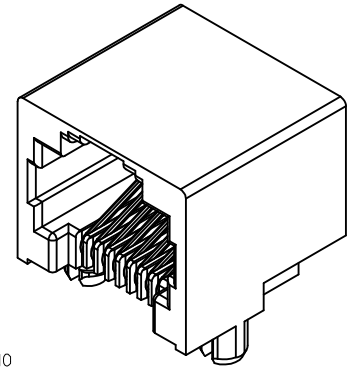
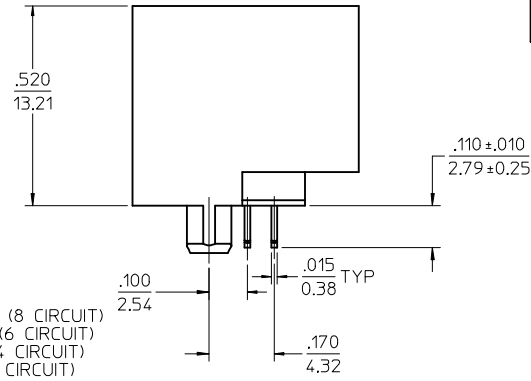
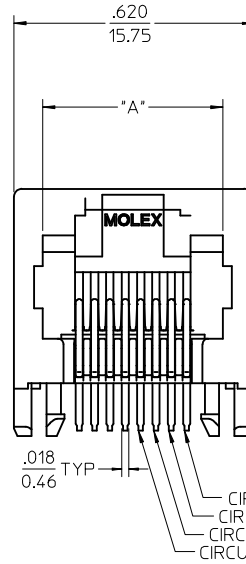
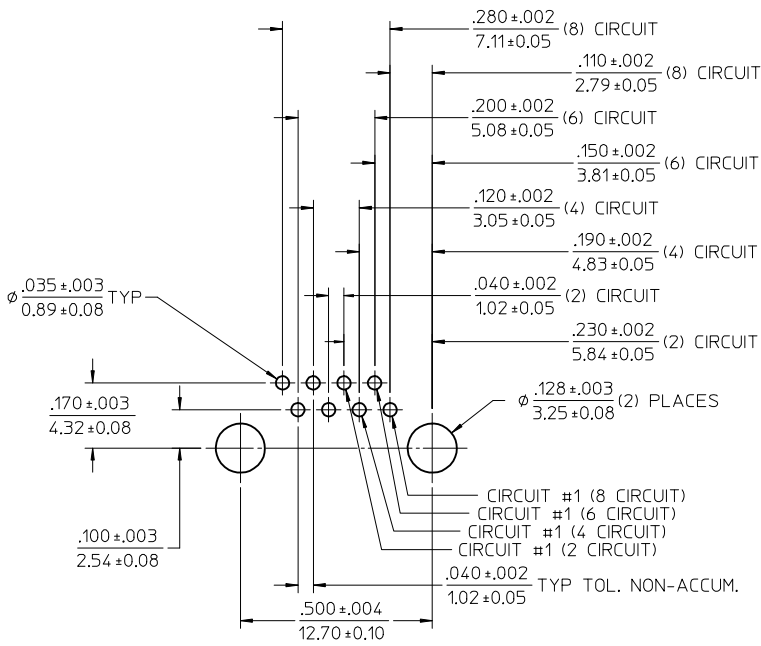
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



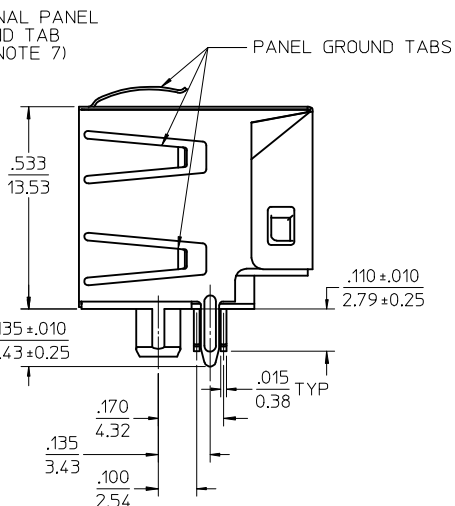
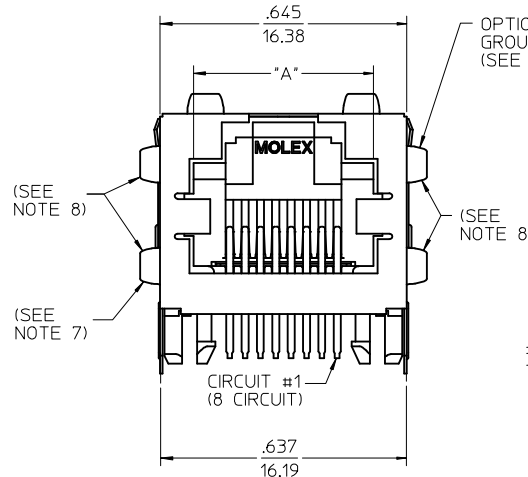
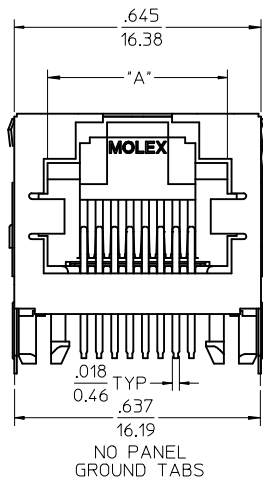
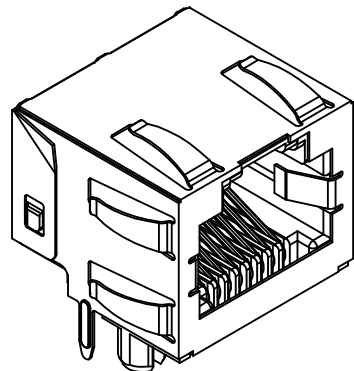
NOTES:

- 1) MATERIAL:  
HOUSING: NYLON(IPA), GLASS FILLED, UL94V-0, COLOR: SEE CHART  
TERMINALS: PHOSPHOR BRONZE
- 2) FINISH:  
TERMINALS:  
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.  
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,  
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
- 3) PRODUCT SPECIFICATION: PS-43860-003.
- 4) PACKAGING SPECIFICATION:  
CONNECTOR ASSEMBLIES PACKAGED IN EXTRUDED TUBES PER MOLEX  
PACKAGING SPECIFICATION PK-43860-004.
- 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- 7) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC  
SPECIFICATION PS-45499-002.

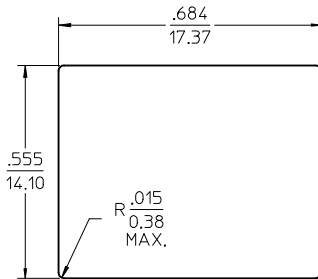


ASSEMBLY MAT. NUM.	CONNECTOR SIZE	DIM "A"	CIRCUITS	HOUSING COLOR
43860-0001	8	.469/11.91	8	BLACK
43860-0002	6	.389/9.88	6	BLACK
43860-0003	6	.389/9.88	4	BLACK
43860-0019	8	.469/11.91	4	BLACK
43860-0020	6	.389/9.88	2	BLACK

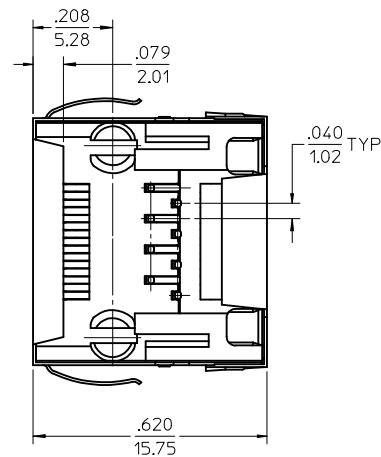
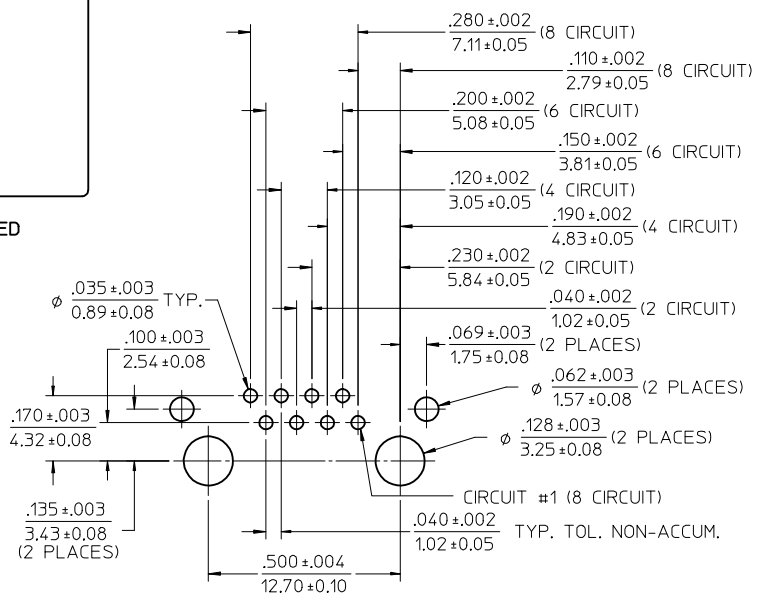
<b>UPDATE VIEWS</b> EC NO: UCP2015-0148 DRAWN: NGUYEN 2014/08/25 CHKD: BELL 2014/08/25 APPR: F. SMITH 2015/05/19 REV: H9	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION			
		4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- 0 PLACE ± ±		DRAWN BY DATE TALEND 1997/02/13		CHECKED BY DATE ROBERTS 1997/03/03		TITLE INVERTED MODULAR JACK ASSEMBLY			
		ANGULAR ±1/2°		APPROVED BY DATE FRY 1997/03/04		MATERIAL NO. SEE CHART					DOCUMENT NO. SD-43860-001
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



- NOTES:
- MATERIAL:  
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0,  
COLOR: BLACK  
TERMINALS: PHOSPHOR BRONZE  
SHIELD: BRASS
  - FINISH:  
TERMINALS:  
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES/  
1.27 MICROMETERS MIN.,  
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES/  
2.54 MICROMETERS MIN.,  
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES/  
1.27 MICROMETERS MIN.  
SHIELD:  
100 MICROINCHES/2.54 MICROMETERS NICKEL OVER  
50 MICROINCHES/1.27 MICROMETERS COPPER  
UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
  - PRODUCT SPECIFICATION: PS-43860-003.
  - PACKAGING SPECIFICATION:  
CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS  
PER MOLEX PACKAGING SPECIFICATION PK-43860-005.  
43860-5025 CONNECTOR ASSEMBLIES PACKAGED IN TAPE AND  
REEL PER MOLEX PACKAGING SPECIFICATION PK-70873-700\*
  - ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
  - CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
  - AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS  
OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY  
MATERIAL NUMBER TABLE.
  - AVAILABLE WITH TOP PANEL GROUND TABS ONLY, PER THE  
ASSEMBLY MATERIAL NUMBER TABLE.
  - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC  
SPECIFICATION PS-45499-002.



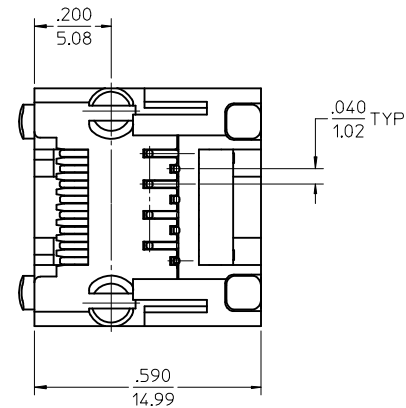
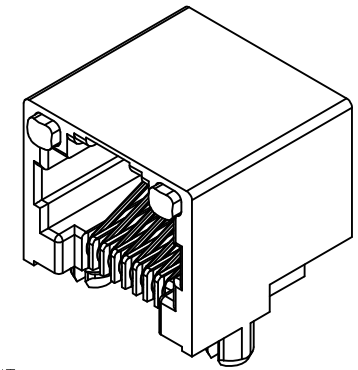
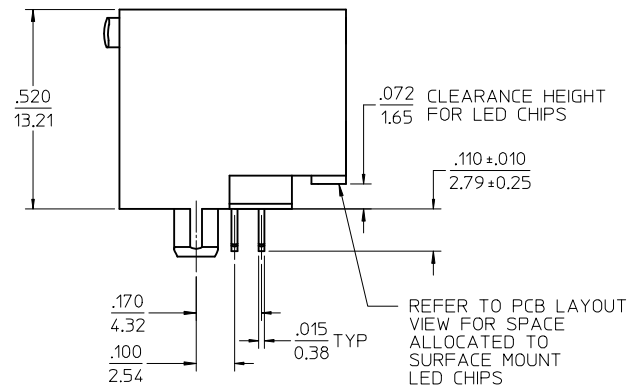
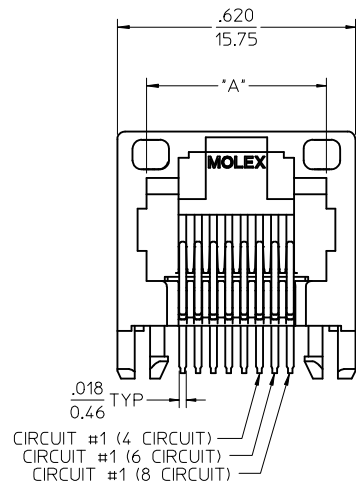
RECOMMENDED  
PANEL  
OPENING



PC BOARD LAYOUT  
COMPONENT SIDE OF BOARD  
RECOMMENDED PCB THICKNESS .062±.005/1.57±.013

ASSEMBLY MAT. NUM.	CONNECTOR SIZE	DIM "A"	CIRCUITS	PANEL GROUND TABS	PACKAGING OPTION
43860-0004	8	.469/11.91	8	ALL	TRAY
43860-0005	6	.389/9.88	6	ALL	TRAY
43860-0006	6	.389/9.88	4	ALL	TRAY
43860-0013	8	.469/11.91	8	SEE NOTE #7	TRAY
43860-0014	6	.389/9.88	6	SEE NOTE #7	TRAY
43860-0015	6	.389/9.88	4	SEE NOTE #7	TRAY
43860-0024	6	.389/9.88	2	ALL	TRAY
43860-0025	8	.469/11.91	8	NONE	TRAY
43860-0026	6	.389/9.88	6	NONE	TRAY
43860-0027	6	.389/9.88	4	NONE	TRAY
43860-0031	8	.469/11.91	8	SEE NOTE #8	TRAY
43860-5025	8	.469/11.91	8	NONE	TAPE

<b>SEE SHEET 1</b> EC NO: UCP2015-0148 DRAWING: NGUYEN 2014/08/25 CHKD: J.BELL 2014/08/25 APPR: F.S.MITH 2015/05/19 H9	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> <tr> <td>4 PLACES</td> <td>± .005</td> <td>± .0002</td> </tr> <tr> <td>3 PLACES</td> <td>± .005</td> <td>± .010</td> </tr> <tr> <td>2 PLACES</td> <td>± .025</td> <td>± .005</td> </tr> <tr> <td>1 PLACE</td> <td>± .005</td> <td>± .005</td> </tr> <tr> <td>0 PLACE</td> <td>±</td> <td>±</td> </tr> </table>		mm	INCH	4 PLACES	± .005	± .0002	3 PLACES	± .005	± .010	2 PLACES	± .025	± .005	1 PLACE	± .005	± .005	0 PLACE	±	±	DIMENSION STYLE <b>IN/MM</b>	SCALE <b>4:1</b>	DESIGN UNITS <b>INCH</b>	THIRD ANGLE PROJECTION
				mm	INCH																			
			4 PLACES	± .005	± .0002																			
			3 PLACES	± .005	± .010																			
2 PLACES	± .025	± .005																						
1 PLACE	± .005	± .005																						
0 PLACE	±	±																						
DRAWN BY TALEND 1997/02/13		DATE 1997/02/13		<b>INVERTED MODULAR JACK ASSEMBLY</b>																				
CHECKED BY ROBERTS 1997/03/03		DATE 1997/03/03																						
APPROVED BY FRY 1997/03/04		DATE 1997/03/04		<b>molex</b>																				
MATERIAL NO. <b>SEE CHART</b>		DOCUMENT NO. <b>SD-43860-001</b>					SHEET NO. <b>2 OF 5</b>																	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS																								
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																								

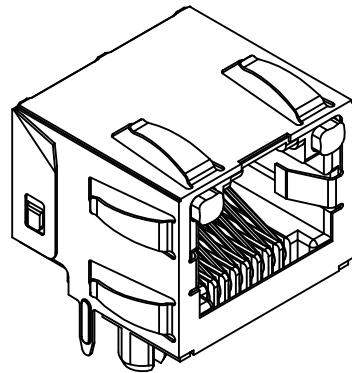


NOTES:

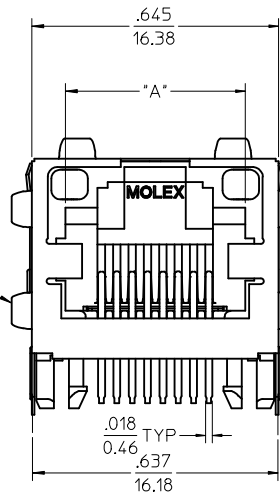
- 1) MATERIAL:  
 HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK  
 TERMINALS: PHOSPHOR BRONZE  
 LIGHT PIPES:  
 POLYCARBONATE - WAVE OR HAND SOLDER ONLY  
 (NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW SOLDER PROCESSES)  
 POLYSULFONE - MAXIMUM REFLOW TEMPERATURE 400°F (205°C)
- 2) FINISH:  
 TERMINALS:  
 SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,  
 SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,  
 WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
- 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
- 4) PACKAGING SPECIFICATION:  
 CONNECTOR ASSEMBLIES PACKAGED IN EXTRUDED TUBES PER MOLEX PACKAGING SPECIFICATION PK-43860-004.
- 5) APPLICATION SPECIFICATION: AS-43860-001
- 6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 7) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- 8) REFER TO SHEET (5) OF (5) FOR RECOMMENDED PCB LAYOUT.
- 9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

ASSEMBLY MAT. NUM.	LIGHT PIPE MATERIAL	CONNECTOR SIZE	DIM "A"	CIRCUITS
43860-0007	POLYCARBONATE	8	.469/11.91	8
43860-0008	POLYCARBONATE	6	.389/9.88	6
43860-0009	POLYCARBONATE	6	.389/9.88	4
43860-0021	POLYSULFONE	8	.469/11.91	8
43860-0022	POLYSULFONE	6	.389/9.88	6
43860-0023	POLYSULFONE	6	.389/9.88	4

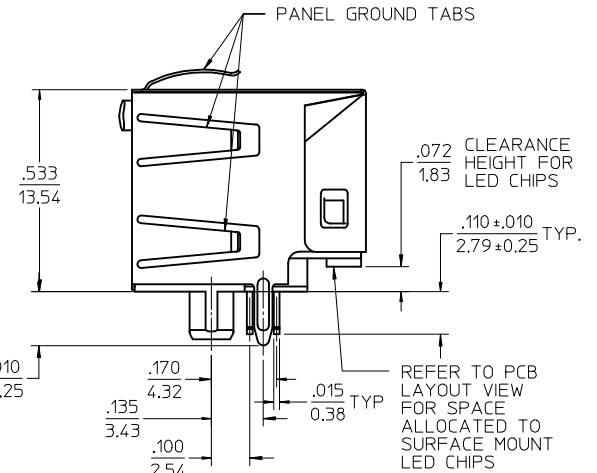
SEE SHEET 1 EC NO: UCP2015-0148 DRAWN: NGUYEN CHKD: BELL APPR: F. SMITH	2014/08/25 2014/08/25 2015/05/19	DESCRIPTION H9	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
			▽=0	mm INCH	IN/MM	4:1	INCH	DRAWN BY DATE TALEND 1997/02/13 CHECKED BY DATE ROBERTS 1997/03/03 APPROVED BY DATE FRY 1997/03/04	TITLE INVERTED MODULAR JACK ASSEMBLY	
			▽=0	4 PLACES ± --- ± ---	3 PLACES ± --- ± .010	2 PLACES ± 0.25 ± ---	1 PLACE ± --- ± ---			0 PLACE ± ±
			▽=0	ANGULAR ±1/2°			MATERIAL NO.			DOCUMENT NO.
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE CHART	SD-43860-001	3 OF 5					
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										



OPTIONAL PANEL GROUND TAB (SEE NOTE 8)

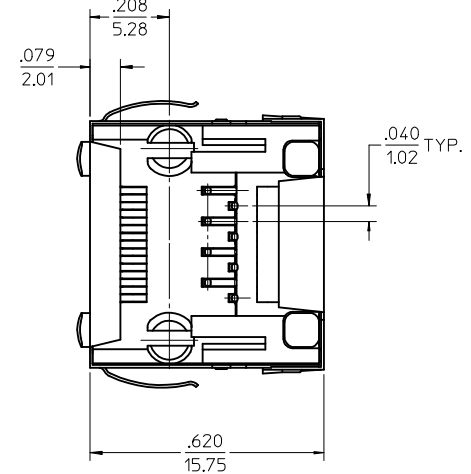
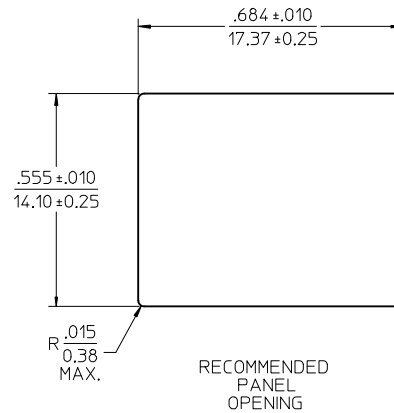


OPTIONAL PANEL GROUND TAB (SEE NOTE 8)



NOTES:

- 1) MATERIAL:  
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK  
TERMINALS: PHOSPHOR BRONZE  
SHIELD: BRASS  
LIGHT PIPES:  
POLYCARBONATE - WAVE OR HAND SOLDER ONLY (NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW SOLDER PROCESSES)  
POLYSULFONE - MAXIMUM REFLOW TEMPERATURE 400°F (205°C)
- 2) FINISH:  
TERMINALS:  
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES/1.27 MICROMETERS MIN.  
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES/2.54 MICROMETERS MIN.  
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES/1.27 MICROMETERS MIN.  
SHIELD:  
100 MICROINCHES/2.54 MICROMETERS OVER 50 MICROINCHES/1.27 MICROMETERS COPPER UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
- 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
- 4) PACKAGING SPECIFICATION:  
CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-43860-005.
- 5) APPLICATION SPECIFICATION: AS-43860-001
- 6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 7) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- 8) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
- 9) REFER TO SHEET (5) OF (5) FOR RECOMMENDED PCB LAYOUT.
- 10) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

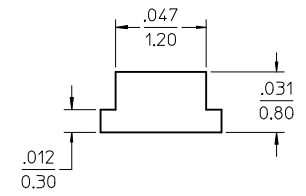
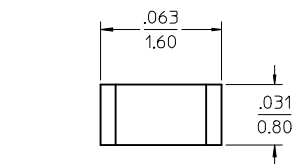
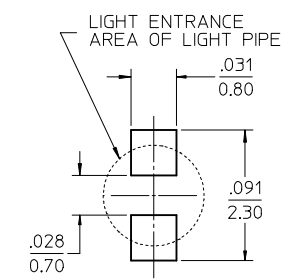
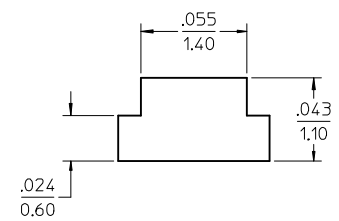
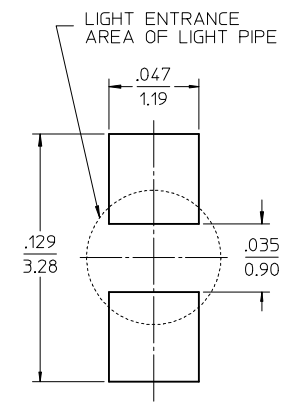
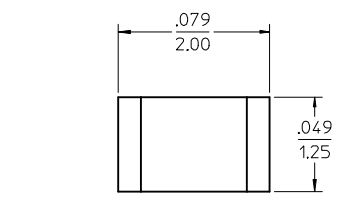
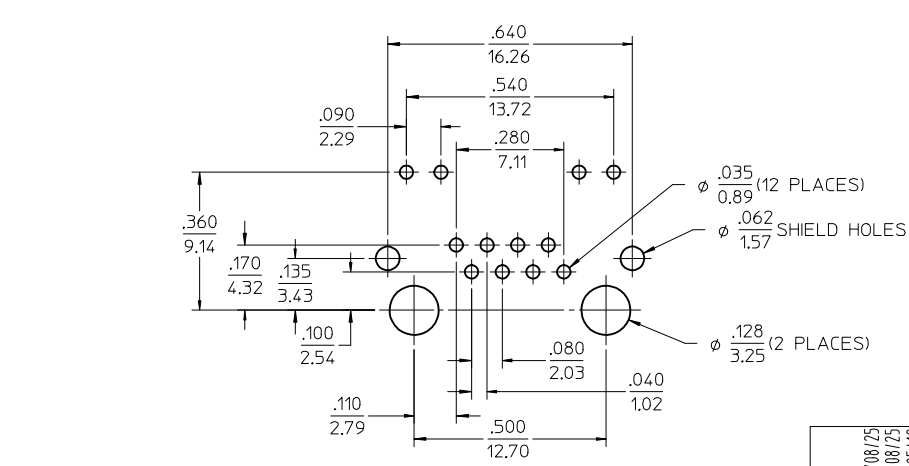
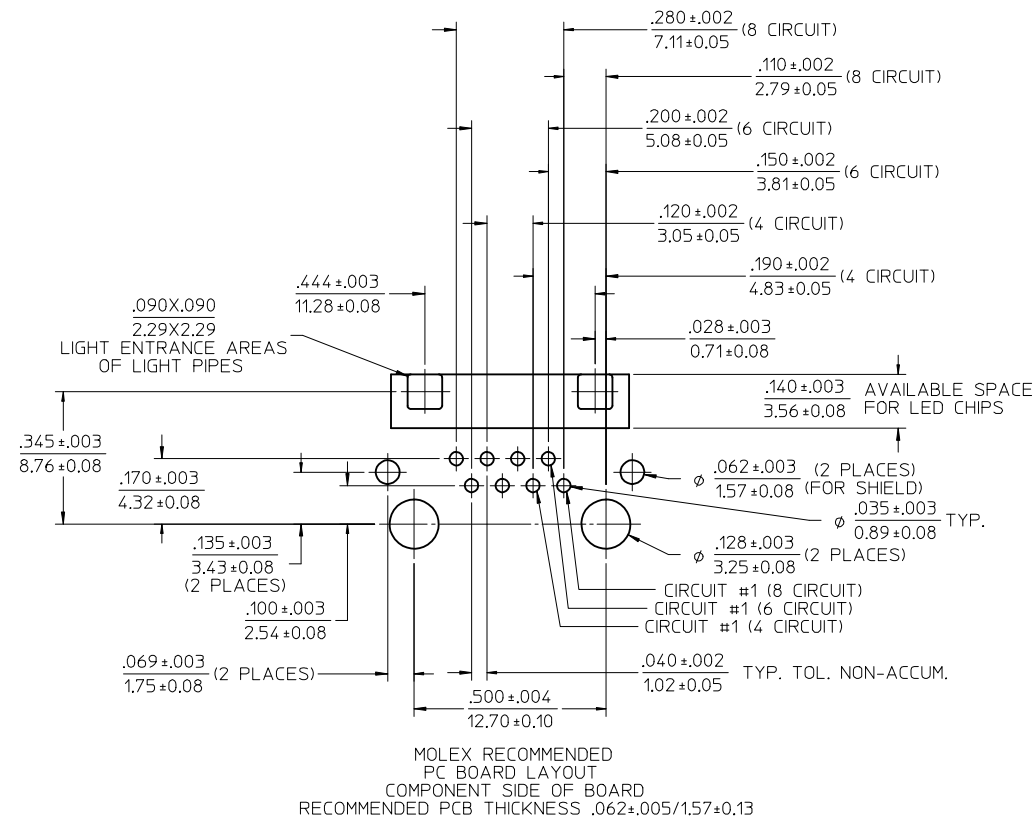


ASSEMBLY MAT. NUM.	LIGHT PIPE MATERIAL	CONNECTOR SIZE	DIM "A"	CIRCUITS	PANEL GROUND TABS
43860-0010	POLYCARBONATE	8	.469/11.91	8	ALL
43860-0011	POLYCARBONATE	6	.389/9.88	6	ALL
43860-0012	POLYCARBONATE	6	.389/9.88	4	ALL
43860-0016	POLYCARBONATE	8	.469/11.91	8	SEE NOTE #8
43860-0017	POLYCARBONATE	6	.389/9.88	6	SEE NOTE #8
43860-0018	POLYCARBONATE	6	.389/9.88	4	SEE NOTE #8
43860-1010	POLYSULFONE	8	.469/11.91	8	ALL
43860-1011	POLYSULFONE	6	.389/9.88	6	ALL
43860-1012	POLYSULFONE	6	.389/9.88	4	ALL
43860-1016	POLYSULFONE	8	.469/11.91	8	SEE NOTE #8
43860-1017	POLYSULFONE	6	.389/9.88	6	SEE NOTE #8
43860-1018	POLYSULFONE	6	.389/9.88	4	SEE NOTE #8

<b>SEE SHEET 1</b> EC NO: UCP2015-0148 DRAWN: NGUYEN 2014/08/25 CHKD: BELL 2014/08/25 APPR: FSMITH 2015/05/19 H9	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>IN/MM</b>		SCALE <b>4:1</b>	DESIGN UNITS <b>INCH</b>	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- 0 PLACE ± ±	mm INCH	DRAWN BY TALEND	DATE 1997/02/13	TITLE <b>INVERTED MODULAR JACK ASSEMBLY</b>			
		ANGULAR ±1/2°		CHECKED BY ROBERTS	DATE 1997/03/03	MATERIAL NO. <b>SEE CHART</b>			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY FRY	DATE 1997/03/04	DOCUMENT NO. <b>SD-43860-001</b>		SHEET NO. <b>4 OF 5</b>	

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION





NOTES:  
1. FOR CROSS REFERENCE OF RECOMMENDED LED'S SEE MOLEX WEB SITE

SEE SHEET 1 EC NO: UCP2015-0148 DRAWN: NGUYEN 2014/08/25 CHKD: J.BELL 2014/08/25 APPR: F.S.MITH 2015/05/19	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION			
				IN/MM		4:1	INCH				
				mm	INCH	DRAWN BY		DATE		TITLE <b>INVERTED MODULAR JACK ASSEMBLY</b>	
				±	±	TALEND		1997/02/13			
						CHECKED BY		DATE			
						ROBERTS		1997/03/03			
						APPROVED BY		DATE			
						FRY		1997/03/04			
				ANGULAR ±1/2°		MATERIAL NO.		DOCUMENT NO.			
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-43860-001			
				SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SHEET NO. 5 OF 5			